Product Change Notification: CENO-26IRKP103

Date:

09-Jun-2025

Product Category:

8-Bit Microcontrollers, Memory

Notification Subject:

CCB 6079.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and QMI519 as a new die attach material for selected AT24C04C, AT24C02C, AT24C01C, AT24C32D, AT24C256C, ATtiny25, ATtiny13A, ATtiny13, 25LC256, 25AA256, 25LC128 and 25AA128 device families available in 8L SOIC (.150in).

Affected CPNs:

CENO-26IRKP103_Affected_CPN_06092025.pdf
CENO-26IRKP103_Affected_CPN_06092025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material and QMI519 as a new die attach material for selected AT24C04C, AT24C02C, AT24C01C, AT24C32D, AT24C256C, ATtiny25, ATtiny13A, ATtiny13, 25LC256, 25AA256, 25LC128 and 25AA128 device families available in 8L SOIC (.150in).

Pre and Post Summary Changes:

	Pre Change	**Post Change**
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)

Wire Material	Au	CuPdAu	CuPdAu
Die Attach Material	8390A		QMI519
Molding Compound Material	G600V		G600V
Lead-Frame Material	CDA194		CDA194

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material and QMI519 as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 22 July 2025 (date code: 2530)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2025				**July 2025**				
Work Week	23	24	25	26	27	28	29	30	31
Qual Report Availability		X							
Final PCN Issue Date		X							
Estimated Implementation Date								X	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

June 09, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CENO-26IRKP103 Qual-Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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